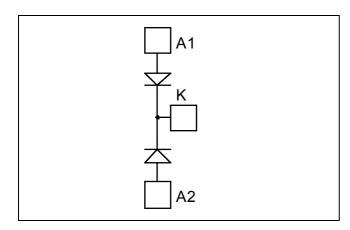


# Dual Common Cathode diodes Power Module

$$V_{RRM} = 600V$$
 $I_{C} = 400A @ Tc = 80°C$ 

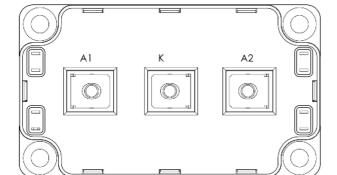


## **Application**

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration



#### **Benefits**

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

## Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
$V_R$	Maximum DC reverse Voltage			600	V	
$V_{RRM}$	Maximum Peak Repetitive Revers	000	v			
T	Maximum Average Forward	Desta 2001	$T_C = 25$ °C	500	,	
I <sub>F(AV)</sub>	Current	Duty cycle = 50%	$T_C = 80$ °C	400	Α	
I <sub>F(RMS)</sub>	RMS Forward Current	Duty cycle = 50%	$T_C = 45^{\circ}C$	500	71	
$I_{FSM}$	Non-Repetitive Forward Surge Cu	rrent 8.3ms	$T_C = 45^{\circ}C$	3000		

These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



# All ratings @ $T_j = 25^{\circ}C$ unless otherwise specified

## **Electrical Characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$V_{\mathrm{F}}$	Diode Forward Voltage	$I_F = 400A$			1.6	2.0	
		$I_F = 800A$			2.0		V
		$I_F = 400A$	$T_{j} = 125^{\circ}C$		1.3		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600V$ $T_j = 25^{\circ}C$ $T_j = 125^{\circ}C$	$T_i = 25^{\circ}C$			750	4
			$T_j = 125$ °C			1000	μΑ
$C_{T}$	Junction Capacitance	$V_R = 600V$			760		pF

**Dynamic Characteristics** 

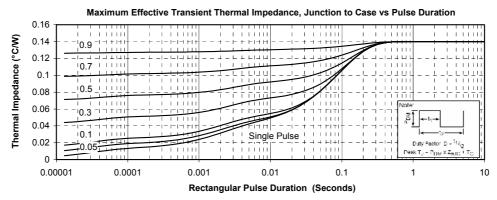
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$t_{rr}$	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 400A/\mu s$	$T_j = 25^{\circ}C$		34		ns
t <sub>rr</sub>	Reverse Recovery Time		$T_j = 25$ °C		160		- ns
			$T_{j} = 125^{\circ}C$		220		
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 400A$ $V_R = 400V$	$T_j = 25$ °C		1.16		μС
Vп	Reverse Recovery Charge	$di/dt = 800A/\mu s$	$T_{j} = 125^{\circ}C$		6.12		μС
$I_{RRM}$	Reverse Recovery Current		$T_j = 25$ °C		20		A
	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		52		
$t_{rr}$	Reverse Recovery Time	$I_F = 400A$ $V_R = 400V$ $di/dt = 4000A/\mu s$			100		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		11.6		μС
$I_{RRM}$	Reverse Recovery Current				176		A

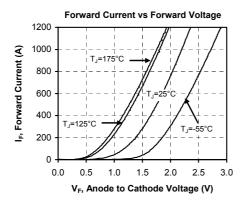
Thermal and package characteristics

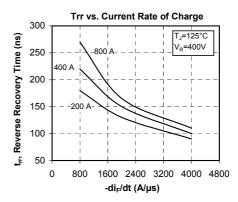
Symbol	Characteristic			Min	Тур	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance					0.14	°C/W
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
$T_{\rm J}$	Operating junction temperature range			-40		175	°C
$T_{STG}$	Storage Temperature Range			-40		125	
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

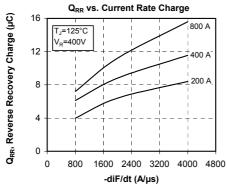


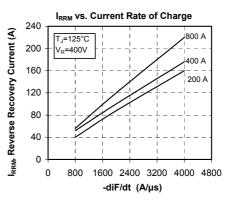
## **Typical Performance Curve**

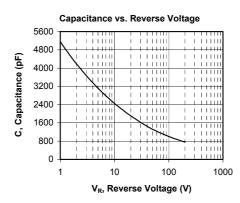


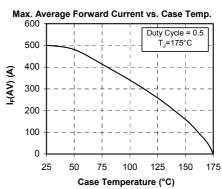








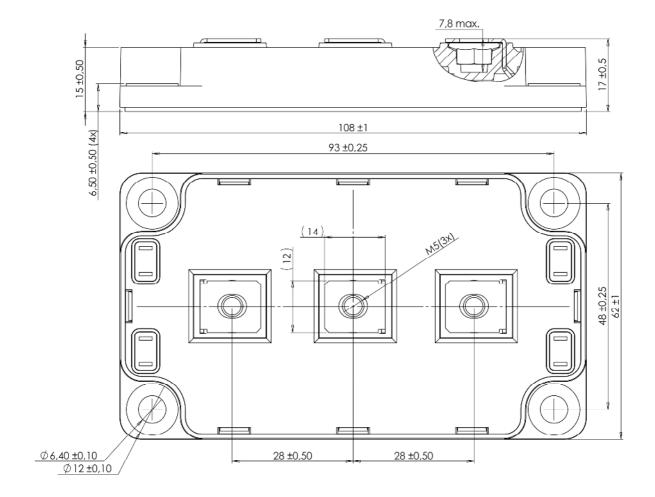




3 - 5



## SP6 Package outline (dimensions in mm)





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